

Patent claims:

1 – 10 (canceled)

11. (new) A method for production of a component having a surface, comprising:
connecting a filling element to the component by a fixing method;
during the fixing method of the filling element and component, using a holder that connects the filling element to the component at temporarily,
wherein the holder has a first holding point on a surface of the component and a second holding point on the filling element; and
removing the holder after the filling element and component have been fixed.

12. (new) The method as claimed in claim 11, wherein the filling element is introduced into a groove in the component, and between the filling element and the component in the groove there is a gap in which a spacer is arranged.

13. (new) The method as claimed in claim 12, wherein the spacer is arranged in the gap before the holder is fitted.

14. (new) The method as claimed in claim 11, wherein the fixing method used for the filling element and component is a soldering method.

15. (new) The method as claimed in claim 11, wherein the fixing method used for the filling element and component is a welding method.

16. (new) The method as claimed in claim 11, wherein the fixing method used for the filling element and component is a laser welding method.

17. (new) The method as claimed in claim 11, wherein the fixing method used for the filling element and component is an electron beam welding method.

18. (new) The method as claimed in claim 11, wherein two holders are used.
19. (new) The method as claimed in claim 11, wherein the holder is M-shaped.
20. (new) The method as claimed in claim 11, wherein a first end of the M shape of the holder is fixed to a first holding point on the component, the middle of the M shape of the holder is fixed to a second holding point on the filling element, and a second end of the M shape of the holder is fixed to a third holding point on the component.